

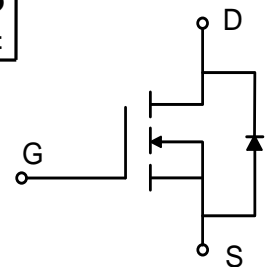
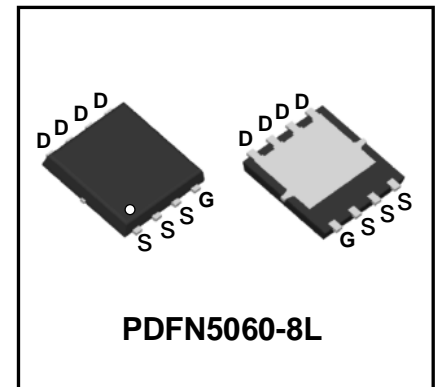
## 60V N-Channel Enhancement Mode Power MOSFET

### Description

WMB025N06LG2 uses Wayon's 2<sup>nd</sup> generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.

### Features

- $V_{DS} = 60V$ ,  $I_D = 158A$ (Silicon Limited)  
 $R_{DS(on)} < 2.8m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 3.8m\Omega$  @  $V_{GS} = 4.5V$
- Low Gate Charge
- 100% EAS Guaranteed
- High Speed Power Switching, Logic Level
- Low  $R_{DS(ON)}$



### Applications

- Hard Switching and High Speed Circuit
- DC/DC Conversion
- Synchronous Rectification in SMPS

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup> (Silicon Limited)	$I_D$	$T_C=25^\circ C$	158
		$T_C=100^\circ C$	100
Continuous Drain Current <sup>1</sup> (Package Limited)	$T_C=25^\circ C$	58	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	401	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	61	mJ
Avalanche Current	$I_{AS}$	35	A
Total Power Dissipation <sup>4</sup>	$T_C=25^\circ C$	$P_D$	112
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	56	$^\circ C/W$
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	1.12	$^\circ C/W$

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60	-	-	V	
Gate-body Leakage Current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 60V, V_{GS} = 0V$	$T_J = 25^\circ\text{C}$	-	-	1	$\mu A$
			$T_J = 100^\circ\text{C}$	-	-	100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.6	2.4	V	
Drain-Source on-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	2.5	2.8	m $\Omega$	
		$V_{GS} = 4.5V, I_D = 20A$	-	3.2	3.8		
Forward Transconductance <sup>2</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 20A$	-	59	-	S	
<b>Dynamic Characteristics</b>							
Input Capacitance	$C_{iss}$	$V_{DS} = 30V, V_{GS} = 0V, f = 1\text{MHz}$	-	4390	-	$\mu F$	
Output Capacitance	$C_{oss}$		-	1250	-		
Reverse Transfer Capacitance	$C_{rss}$		-	65	-		
<b>Switching Characteristics</b>							
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$	-	2.0	-	$\Omega$	
Total Gate Charge	$Q_g$	$V_{GS} = 10V, V_{DS} = 30V, I_D = 20A$	-	35	-	nC	
Total Gate Charge	$Q_g$		-	75	-		
Gate-Source Charge	$Q_{gs}$		-	10	-		
Gate-Drain Charge	$Q_{gd}$		-	14.5	-		
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 30V, R_G = 10\Omega, I_D = 20A$	-	14.5	-	nS	
Rise Time	$t_r$		-	10.5	-		
Turn-off Delay Time	$t_{d(off)}$		-	57	-		
Fall Time	$t_f$		-	16.8	-		
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 20A, V_{GS} = 0V$	-	-	1.2	V	
Body Diode Reverse Recovery Time	$t_{rr}$	$V_R = 30V, I_F = 20A, di/dt = 300A/\mu s$	-	45	-	nS	
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	87	-	nC	

## Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating. The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1\text{mH}, I_{AS} = 35A$
- The power dissipation is limited by  $150^\circ\text{C}$  junction temperature

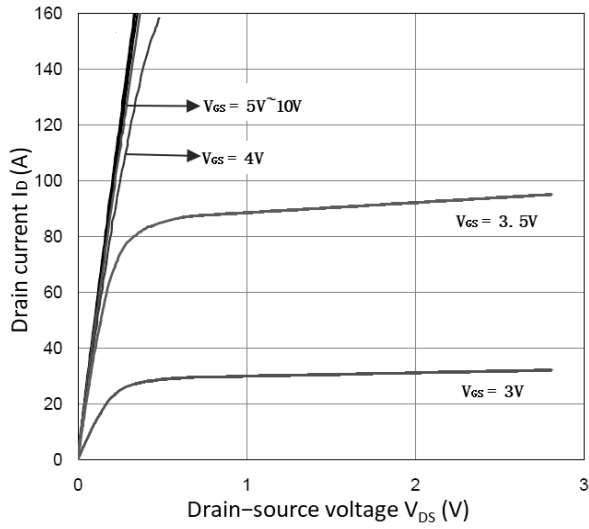


Figure 1. Output Characteristics

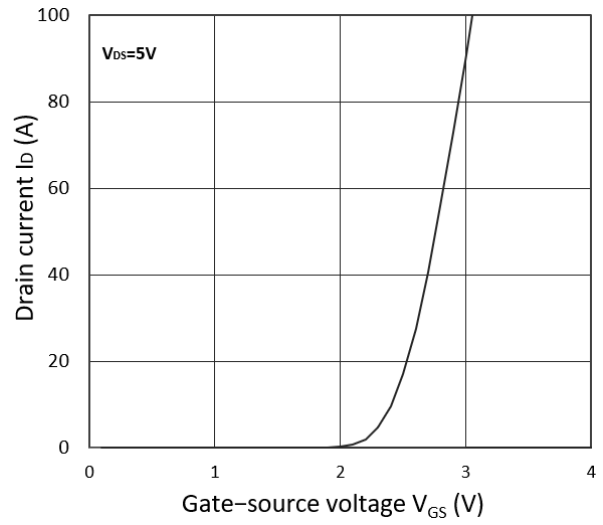


Figure 2. Transfer Characteristics

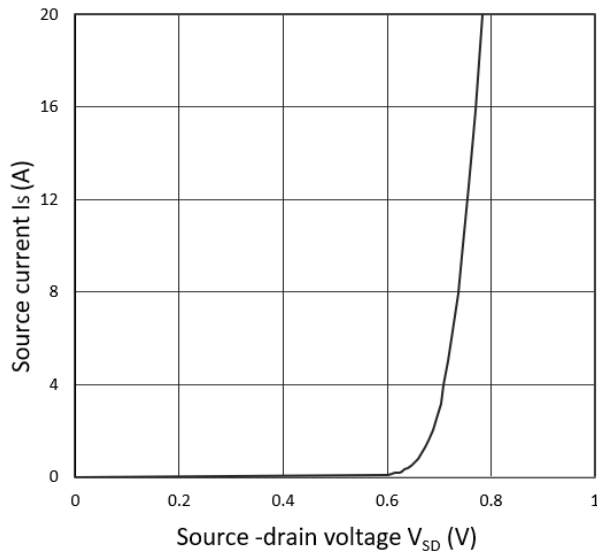


Figure 3. Forward Characteristics of Reverse

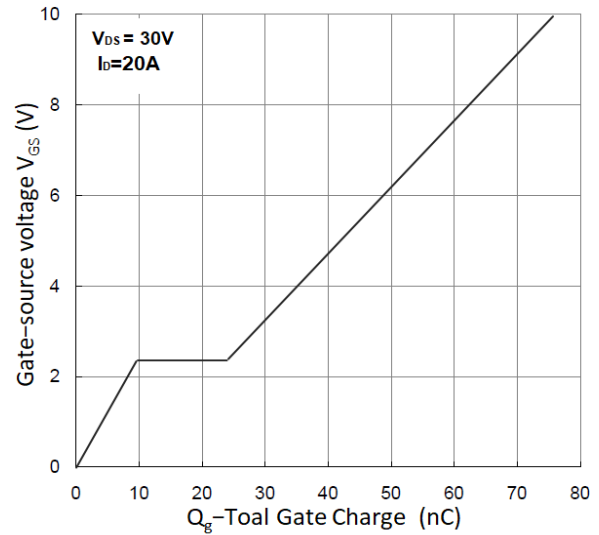


Figure 4. Gate Charge Characteristics

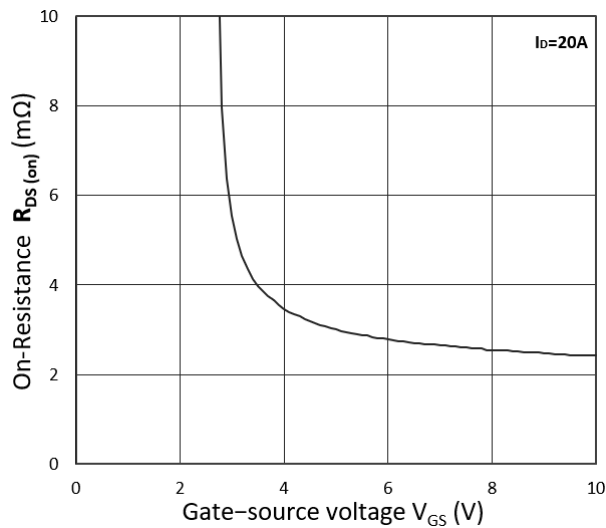


Figure 5.  $R_{DS(ON)}$  vs.  $V_{GS}$

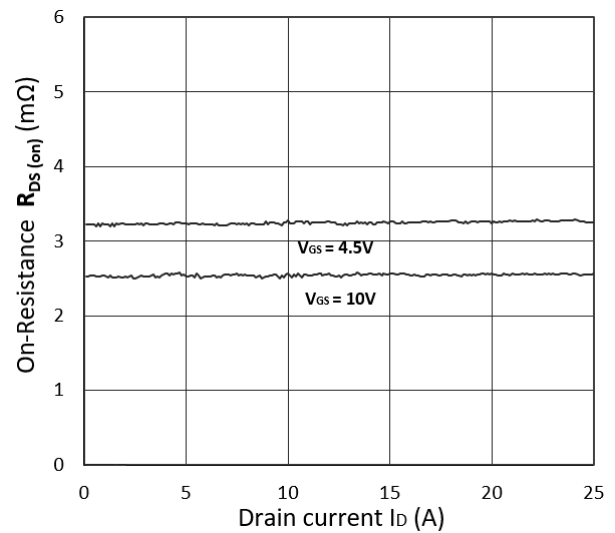


Figure 6.  $R_{DS(ON)}$  vs.  $I_D$

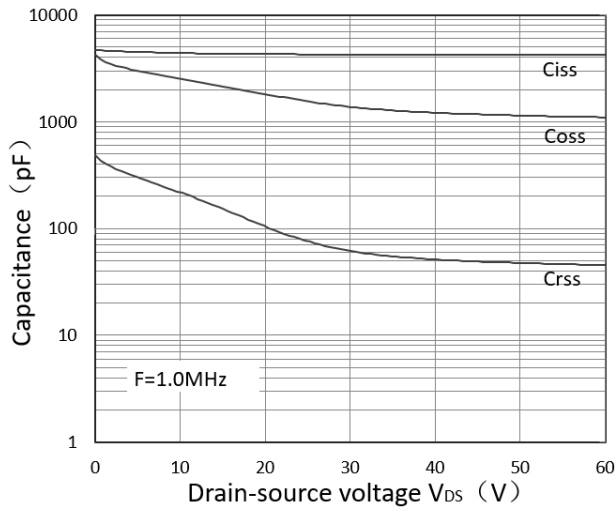


Figure 7. Capacitance Characteristics

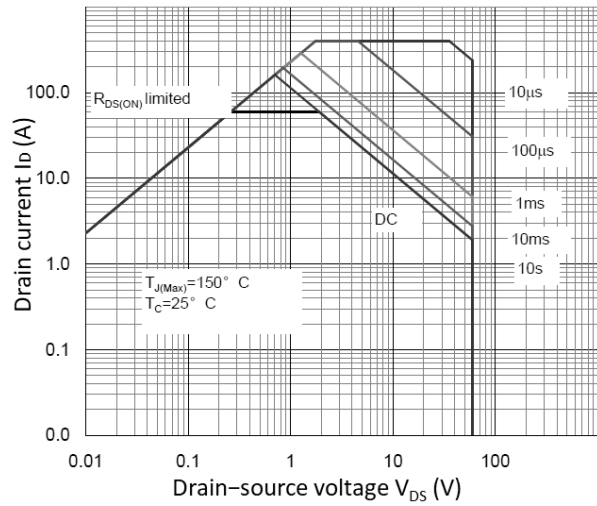


Figure 8. Safe Operating Area

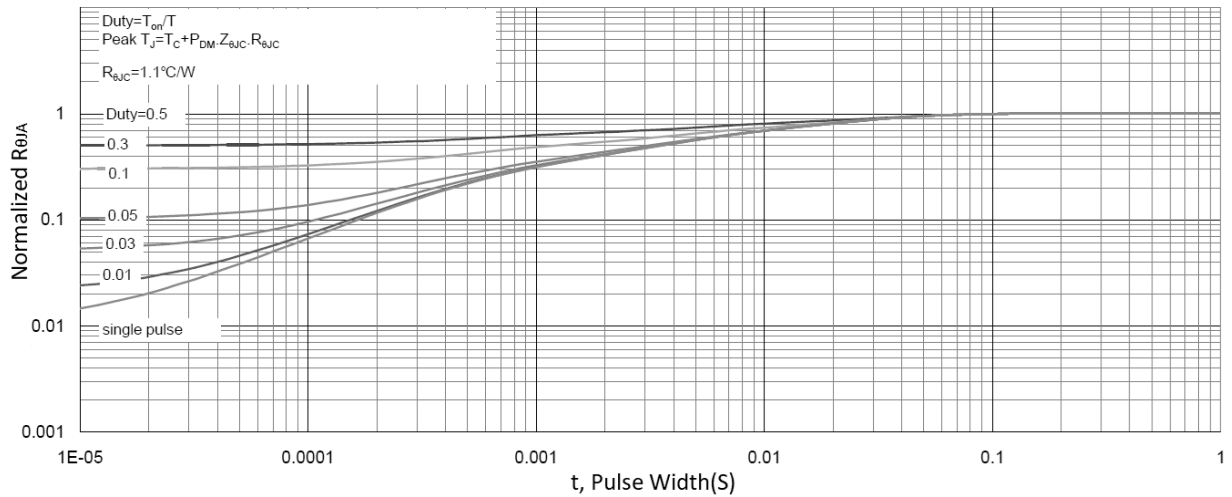


Figure 9. Normalized Maximum Transient Thermal Impedance

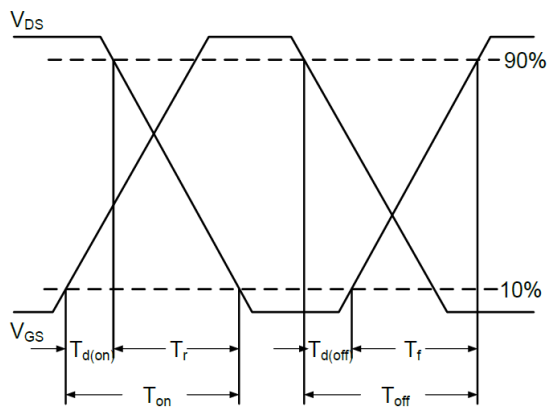


Figure 10. Switching Time Waveform

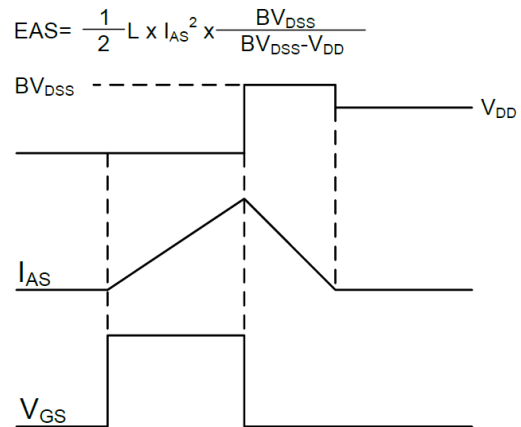
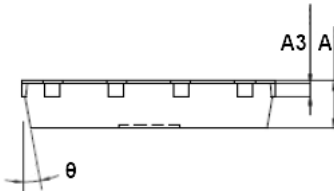
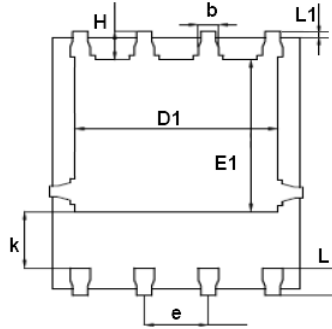
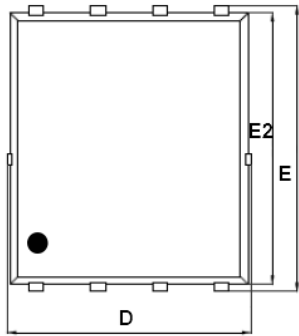


Figure 11. Unclamped Inductive Switching Waveform

## Mechanical Dimensions for PDFN5060-8L



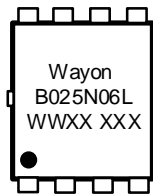
## COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.30	3.92
E2	5.65	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.61
$\theta$	0°	12°

## Ordering Information

Part	Package	Marking	Packing method
WMB025N06LG2	PDFN5060-8L	B025N06L	Tape and Reel

## Marking Information



B025N06L = Device code

WWXX XXX= Date code

## Contact Information

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